HOSTAFORM® C 52021 ECO-B

HOSTAFORM®

Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GNR, 06-002 POM copolymer Extremely easy flowing Injection molding type for very thin-walled precision molded parts with unfavourite flow-path-wallthickness relation; permits processing at reduced temperature and also shorter cycle times; for mechanical lower requirements; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. Monomers and additives are listed in EU-Regulation (EU) 10/2011 FDA compliant according to 21 CFR 177.2470 UL-registration in natural a thickness more than 0.81 mm, in black a thickness more than 1.5 mm as UL 94 HB, temperature index UL 746 B for a thickness of 1.5 mm, electrical 105 °C, mechanical 90 °C Burning rate ISO 3795 and FMVSS 302 < 75 mm/min for a thickness more than 1 mm. Ranges of applications: For very thin-walled precision molded parts with unfavourite flow-path-wallthickness relation; permits processing at reduced temperature and also shorter cycle times. FDA = Food and Drug Administration (USA) FMVSS = Federal Motor Vehicle Safety Standard (USA) UL = Underwriters Laboratories (USA).
ECO-B: Hostaform ECO-B is a POM-Copolymer with the same properties and performance as standard grades but produced with sustainability in mind. Using a mass-balance approach, biogenic feedstocks are used to offset the use of fossil-based raw materials and decrease greenhouse gas emissions. The process is audited and certified according to the ISCC Plus mass balance approach.

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	39	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	1.9	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	3000	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	65	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	7	%	ISO 527-1/-2
Nominal strain at break	15	%	ISO 527-1/-2
Flexural modulus	2850	MPa	ISO 178
Flexural stress at 3.5%	77	MPa	ISO 178
Tensile creep modulus, 1h	2500	MPa	ISO 899-1
Tensile creep modulus, 1000h	1300	MPa	ISO 899-1
Charpy impact strength, 23°C	150	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	150	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	5	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	5	kJ/m^2	ISO 179/1eA
Ball indentation hardness, H 358/30	148	MPa	ISO 2039-1
Poisson's ratio	0.37[C]		

[C]: Calculated

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Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	106	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	110	E-6/K	ISO 11359-1/-2
Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2
Specific heat capacity of melt	2060	J/(kg K)	ISO 22007-4

Flammability

Burning Behav. at 1.5mm nom. thickn.	HB	class	IEC 60695-11-10
Thickness tested	1.5	mm	IEC 60695-11-10
Burning Behav. at thickness h	HB	class	IEC 60695-11-10
Thickness tested	0.81	mm	IEC 60695-11-10
UL recognition	yes		UL 94

Electrical properties

Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4		IEC 62631-2-1
Dissipation factor, 100Hz	30	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50	E-4	IEC 62631-2-1
Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Electric strength	35	kV/mm	IEC 60243-1
Comparative tracking index	600		IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1410	kg/m^3	ISO 1183

Injection

Drying Temperature	120	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.15	%
Melt Temperature Optimum	210	°C
Screw tangential speed	≤0.202	m/s
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa
Ejection temperature	140	°C

Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent

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Special characteristics	High Flow
Sustainability	Bio-Content

Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

The product can then be stored in standard conditions until processed.

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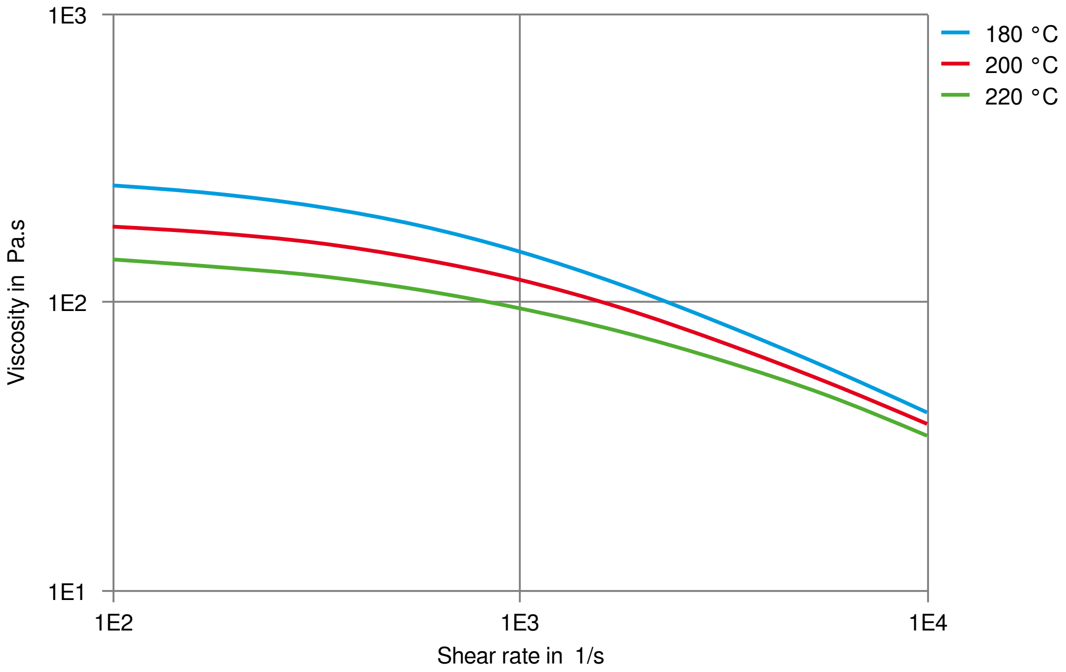
Viscosity-shear rate



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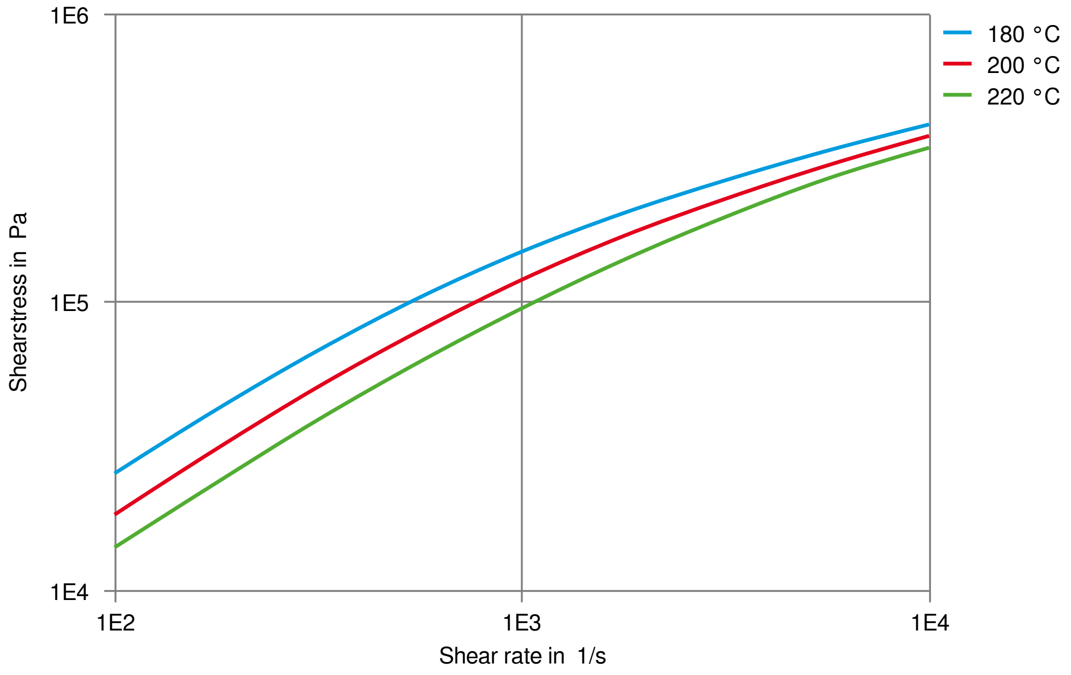
Shearstress-shear rate



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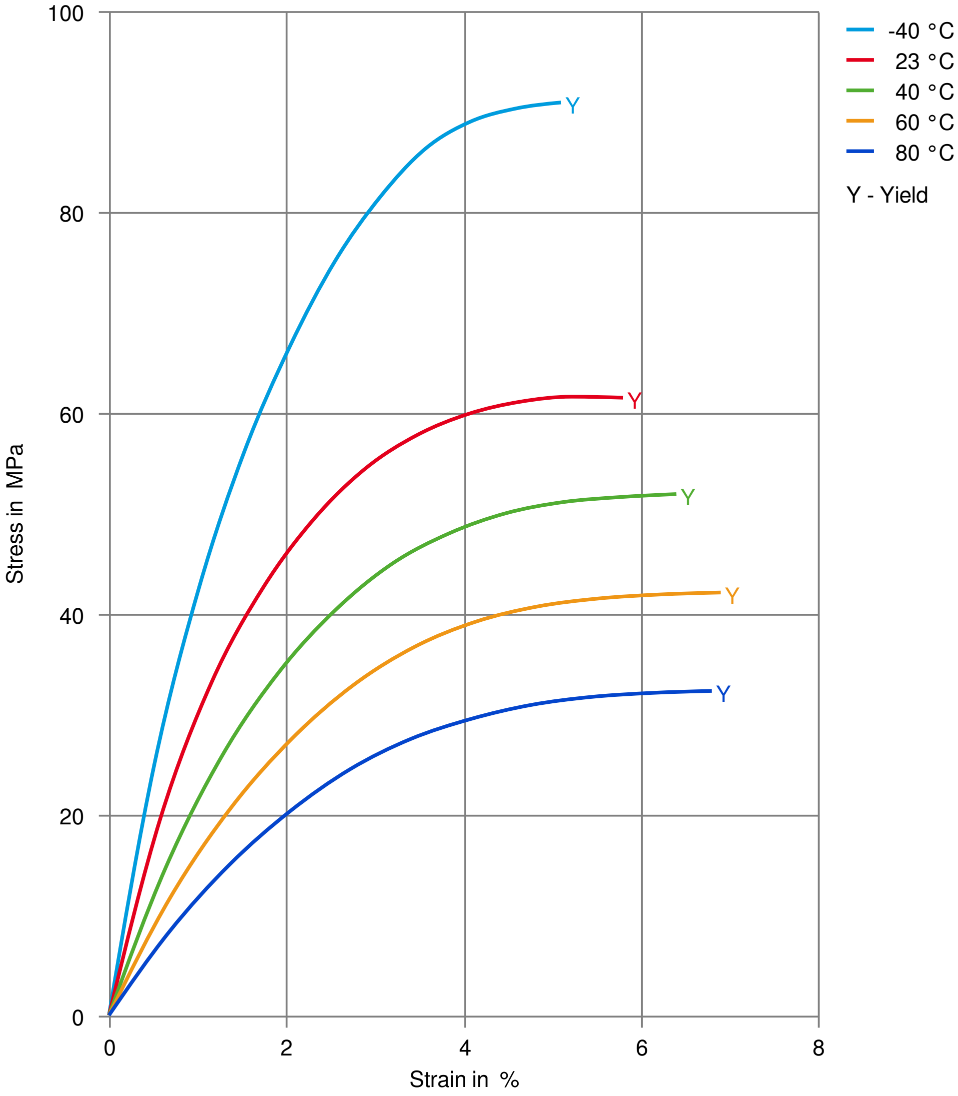
Stress-strain



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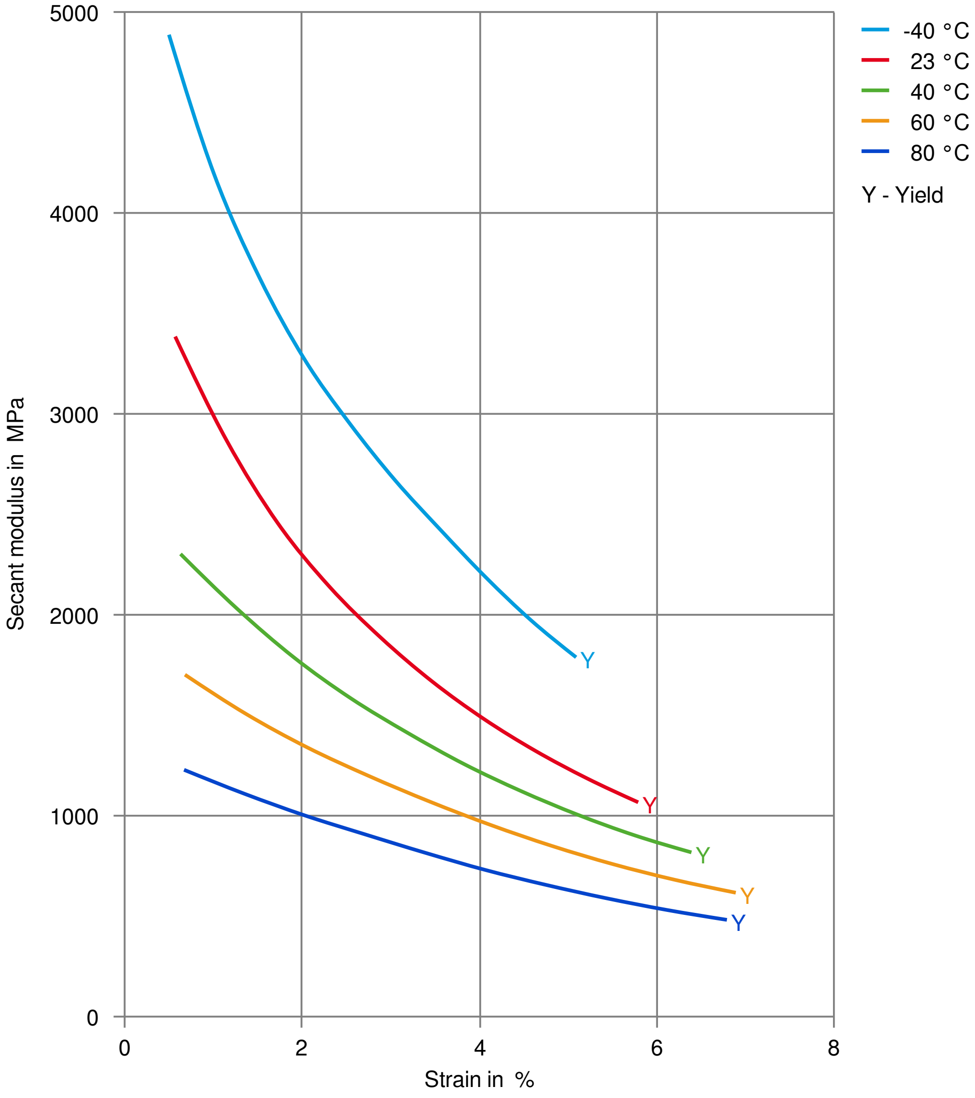
Secant modulus-strain



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